

PRINTER RUSH
(PTO ASSISTANCE)

IIFW

Application :	Examiner :	GAU :
<u>09/475104</u>	<u>Mitchell</u>	<u>2P13</u>
From:	Location: IDC FMF FDC	Date: <u>8-1-05</u>
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<input type="checkbox"/> 1449	<hr/>	<input type="checkbox"/> Continuing Data
<input type="checkbox"/> IDS	<hr/>	<input type="checkbox"/> Foreign Priority
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<input type="checkbox"/> IIFW	<hr/>	<input type="checkbox"/> Fees
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<input type="checkbox"/> DRW	<hr/>	
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<input type="checkbox"/> 312	<hr/>	
<input checked="" type="checkbox"/> SPEC	<u>12-30-99</u>	

[RUSH] MESSAGE: Please verify

On page 4 of the specification submitted on 12-30-99 there is a reference on lines 8 and 9 to Figure 3a and 3b. Figures 3a and 3b do not exist on the drawing sheet of this application.

The spec amendment dated 9-27-01 deleted data on page 7 but not page 4.

Theresa V. Yau
TW

[XRUSH] RESPONSE: Deleted Fig 3a-3b description.

INITIALS: *def*

NOTE: This form will be included as part of the official USPTO record, with the Response document coded as XRUSH.

REV 10/04

BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 is a cross-sectional view of an embodiment of an integrated circuit package of the present invention;

Figures 2a-b show a process for assembling a thermal epoxy within the integrated circuit package.

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12/6/05
~~Figures 3a-b show an alternate process for assembling the thermal epoxy within the package.~~